

<技術介紹>

耐高溫剝離MicroThin™

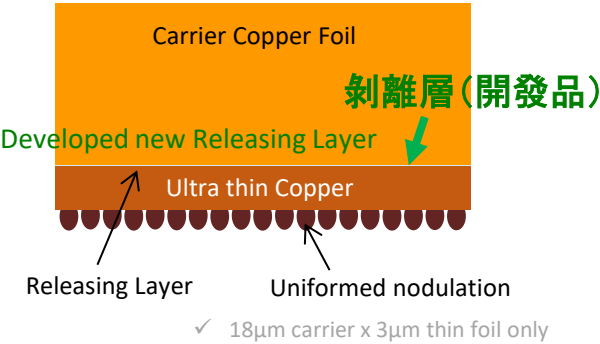
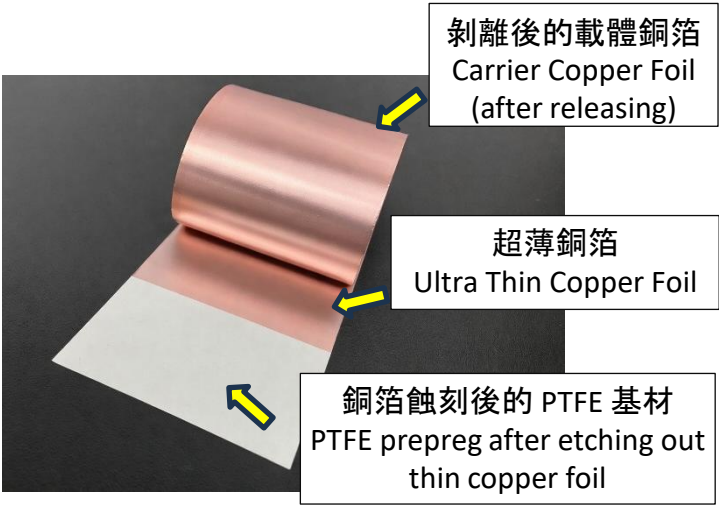


<Technology Introduction> MicroThin™ for high-temperature laminate applications

新開發即使經過高溫壓合仍可剝離的剝離層。

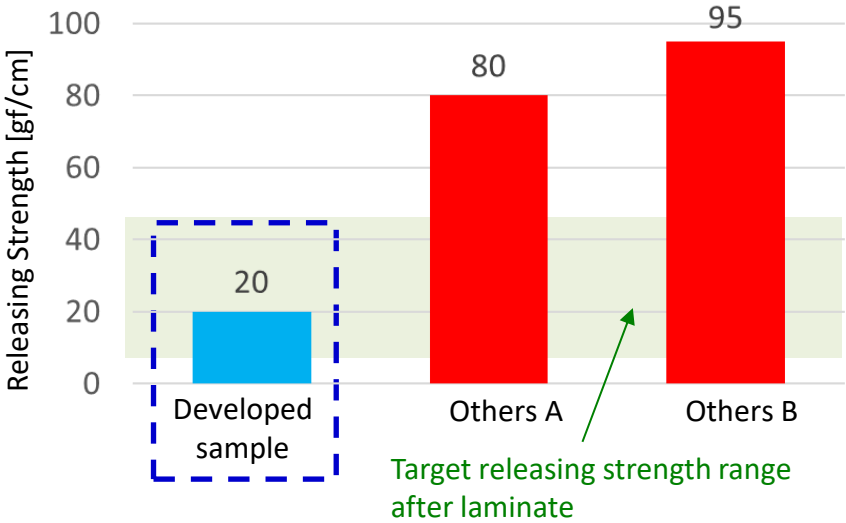
Developed new releasing layer that can be releasing even at high temperature lamination

MicroThin™ Structure



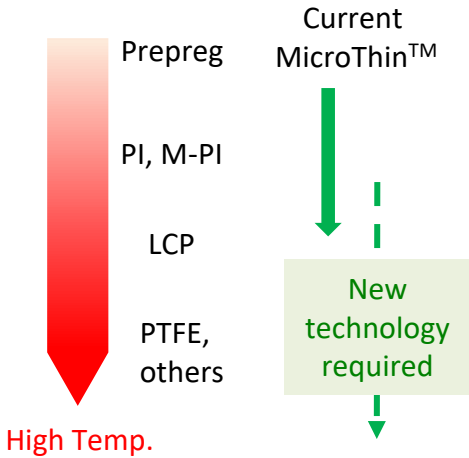
壓合後的剝離強度(370°C, 30min)

Releasing strength after laminating 370°C 30min



高溫壓合示例(示意圖)

Example for high temp. laminate (image)



上述數據為代表值，並非保證值。本資訊截至2026年10月20日，日後可能不經預告進行變更。
These are representative data and are not guaranteed. This information is as of Sep. 9th, 2026, and subject to change without notice.

<Note>

- ✓ 目前僅可提供片狀樣品，捲狀樣品的供應時程尚未確定。
Currently sheet form samples only. Roll form sample availability is not yet be fixed.
- ✓ 若現行 MicroThin™ 可正常剝離，建議繼續使用現行產品系列進行評估。
If any current MicroThin™ line up can be released the carrier foil, we recommend continuing evaluation with current line up.
- ✓ 如需樣品，我們可能會事先確認其應用用途及現行產品系列的評估情況等資訊。
Sample requests are subject to prior discussion regarding the application and previous evaluation situations with current line up.